

### **AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

#### **LISTING OF CLAIMS:**

1. (currently amended): A flexible electronic device comprising: a glass substrate, the glass substrate having a thickness of larger than 0  $\mu\text{m}$  and not larger than 200  $\mu\text{m}$ ; a flexible film disposed on one side of the glass substrate by lamination, the flexible film being different from the material of the glass substrate; ; a sub-strate disposed on the flexible film, the substrate being different from the material of said flexible film and thickness of said substrate is larger than 0  $\mu\text{m}$  and not larger than 200  $\mu\text{m}$ ; and an electrically active thin film device; wherein an electrically active layer of the electrically active thin film device is disposed directly on another side of the glass substrate; wherein said flexible film has a thermal conductivity higher than 0.10 W/cm deg and the thin film device is a film transistor formed of a silicon thin film.

2-5. (canceled).

6. (original): The flexible electronic device according to claim 1, wherein said flexible film is an insulating film.

7-30. (canceled).